

ABSTRACT

The present invention provides: a curable resin composition having a high degree of biomass and having excellent high heat resistance, low dielectric properties, and mechanical properties; and a cured product of the curable resin composition. The curable resin composition has an epoxy resin represented by formula (1) and a lignin-modified phenol resin or a cashew-modified phenol resin. (In formula (1), n is the average number of repetitions and denotes a real number within the range $1 < n < 15$.)

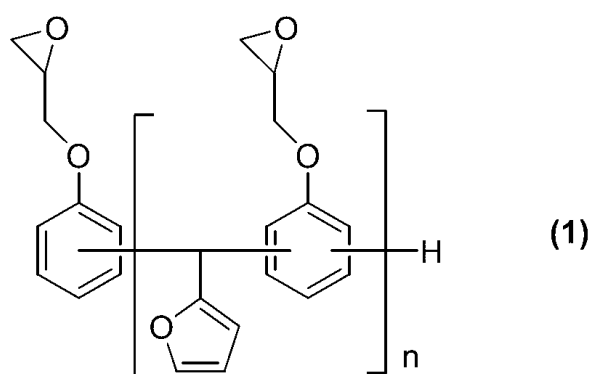


FIG. 1